

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ritzdorf et al.)
)
For: Method and Apparatus for)
Low-Temperature Annealing of)
Metallization Microstructures in)
The Production of a Microelectronic)
Device)
Serial No.: Not Yet Assigned)
)
Filed: Herewith)

7/10
11/20/99

AMENDMENT UNDER 37 C.F.R. § 1.607

Pursuant to 37 C.F.R. §1.607, Applicants respectfully request that an interference be declared between this application and U.S. Patent No. 6,136,163. Applicants request that the above-identified application be amended as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

On page 1, line 9, amend "Not Applicable" after "CROSS-REFERENCE TO RELATED APPLICATIONS" to This is a continuation application of USSN 09/386,734 filed August 31, 1999, which is a continuation of International PCT Patent Application No. PCT/US99/02504, designating the US, filed February 4, 1999, entitled METHOD AND APPARATUS FOR LOW TEMPERATURE ANNEALING OF METALLIZATION MICRO-STRUCTURES IN THE PRODUCTION OF A MICROELECTRONIC DEVICE, which claims priority from US Patent Application Serial No. 09/018,783, filed February 4, 1998, and US Patent Application Serial No. 60/087,432, filed June 1, 1998.--

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